

L Number	Hits	Search Text	DB	Time stamp
-	90852	dielectric adj3 constant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:45
-	37207	low near3 ((dielectric adj3 constant) or k)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:45
-	1583994	oxide or dioxide or sio or "sio.sub."\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:02
-	454908	(c or carbon) with (oxide or dioxide or sio or "sio.sub."\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:46
-	125474	silicon adj3 carbide or sic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:05
-	199881	silicon adj3 nitride or "si.sub.3 n.sub.4" or "si.sub.3n.sub.4" or sin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:07
-	1645043	adhe\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 15:18
-	294339	rf or radio adj3 frequency	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 16:44
-	294826	carbon adj2 (oxide or dioxide) or "co.sub.2"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:31
-	1557693	dielectric or insulator or insulating or insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:43
-	83646	adhe\$6 with (dielectric or insulator or insulating or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:49
-	6696	(c or carbon) with dop\$4 with (oxide or dioxide or sio or "sio.sub."\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:47
-	11926	((c or carbon) with dop\$4 with (oxide or dioxide or sio or "sio.sub."\$2)) or sioc or cdo	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:48
-	636	(adhe\$6 with (dielectric or insulator or insulating or insulation)) and (((c or carbon) with dop\$4 with (oxide or dioxide or sio or "sio.sub."\$2)) or sioc or cdo)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:51

-	207	((adhe\$6 with (dielectric or insulator or insulating or insulation)) and (((c or carbon) with dop\$4 with (oxide or dioxide or sio or "sio.sub."\$2)) or sioc or cdo)) and (rf or radio adj3 frequency)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:50
-	23	adhe\$6 with (((c or carbon) with dop\$4 with (oxide or dioxide or sio or "sio.sub."\$2)) or sioc or cdo) with ((silicon adj3 carbide or sic) or (silicon adj3 nitride or "si.sub.3 n.sub.4" or "si.sub.3n.sub.4" or sin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 16:04
-	4446	(adhe\$6 with (dielectric or insulator or insulating or insulation)) and (low near3 ((dielectric adj3 constant) or k))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 16:05
-	981	((adhe\$6 with (dielectric or insulator or insulating or insulation)) and (low near3 ((dielectric adj3 constant) or k))) and (rf or radio adj3 frequency)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 16:06
-	156	((adhe\$6 with (dielectric or insulator or insulating or insulation)) and (low near3 ((dielectric adj3 constant) or k))) and (rf or radio adj3 frequency)) and (((c or carbon) with dop\$4 with (oxide or dioxide or sio or "sio.sub."\$2)) or sioc or cdo)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 16:09
-	72	((adhe\$6 with (dielectric or insulator or insulating or insulation)) and (low near3 ((dielectric adj3 constant) or k))) and (rf or radio adj3 frequency)) and (((c or carbon) with dop\$4 with (oxide or dioxide or sio or "sio.sub."\$2)) or sioc or cdo) and (carbon adj2 (oxide or dioxide) or "co.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 16:45
-	37207	low near3 ((dielectric adj3 constant) or k)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:14
-	1481	438/778.ccls. or 438/788.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:16
-	1736	(438/778.ccls. or 438/788.ccls.) or 438/790.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:17
-	535	(low near3 ((dielectric adj3 constant) or k)) and ((438/778.ccls. or 438/788.ccls.) or 438/790.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:17
-	1645043	adhe\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:17
-	244	((low near3 ((dielectric adj3 constant) or k)) and ((438/778.ccls. or 438/788.ccls.) or 438/790.ccls.)) and adhe\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:58
-	1257339	(upper or top or first or second) near3 portion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:00

-	1226898	((lower or bottom or first or second) near3 portion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:01
-	937920	((upper or top or first or second) near3 portion) same ((lower or bottom or first or second) near3 portion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:02
-	308	((upper or top or first or second) near3 portion) with (low near3 ((dielectric adj3 constant) or k))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:02
-	287	((lower or bottom or first or second) near3 portion) with (low near3 ((dielectric adj3 constant) or k))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:02
-	239	((upper or top or first or second) near3 portion) with (low near3 ((dielectric adj3 constant) or k))) same (((lower or bottom or first or second) near3 portion) with (low near3 ((dielectric adj3 constant) or k)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:02
-	90	((upper or top or first or second) near3 portion) with (low near3 ((dielectric adj3 constant) or k))) same (((lower or bottom or first or second) near3 portion) with (low near3 ((dielectric adj3 constant) or k)))) and adhe\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:02
-	101429	bi\$1layer or dual\$1layer or composit\$3 adj3 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 11:02
-	1555600	di\$1electric or insulator or insulating or insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:44
-	8166	(bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:44
-	1999872	(dielectric adj3 constant) or k	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:45
-	37257	low near3 ((dielectric adj3 constant) or k)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:46
-	12369	grad\$4 near5 (di\$1electric or k or constant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:47
-	20428	((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:48

-	1404	((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:48
-	1170204	damascence or cu or copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:49
-	18215	(inter\$1layer near4 di\$1electric) or ild or idl	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:51
-	202	((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((inter\$1layer near4 di\$1electric) or ild or idl)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:51
-	159	((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((inter\$1layer near4 di\$1electric) or ild or idl)) and (damascence or cu or copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:51
-	327690	((dielectric adj3 constant) or k) adj5 (1\$2 or 2\$2 or 3\$2 or 4\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:27
-	868	((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:12
-	381929	barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:13
-	5715	((inter\$1layer near4 di\$1electric) or ild or idl) and barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:14
-	64414	(damascence or cu or copper) and barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:14
-	454	((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((inter\$1layer near4 di\$1electric) or ild or idl) and barrier) or ((damascence or cu or copper) and barrier))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:15

-	868	((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((inter\$1layer near4 di\$1electric) or ild or idl)) and (damascence or cu or copper)) or (((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))) or (((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and (((inter\$1layer near4 di\$1electric) or ild or idl) and barrier) or ((damascence or cu or copper) and barrier)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:15
-	611	(((((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((inter\$1layer near4 di\$1electric) or ild or idl)) and (damascence or cu or copper)) or (((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))) or (((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and (((inter\$1layer near4 di\$1electric) or ild or idl) and barrier) or ((damascence or cu or copper) and barrier)))) and (((dielectric adj3 constant) or k) adj5 (1\$2 or 2\$2 or 3\$2 or 4\$2))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:16
-	311368	bi\$1layer or dual\$1layer or multi\$1layer or composit\$3 adj3 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 11:04
-	44430	(bi\$1layer or dual\$1layer or multi\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 11:06
-	56502	((bi\$1layer or dual\$1layer or multi\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 11:06

-	4028	((bi\$1layer or dual\$1layer or multi\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 11:08
-	2552	((((bi\$1layer or dual\$1layer or multi\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 11:11
-	1021	(((((bi\$1layer or dual\$1layer or multi\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))) and (((inter\$1layer near4 di\$1electric) or ild or idl) and barrier) or ((damascence or cu or copper) and barrier))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 11:12
-	700	(((((bi\$1layer or dual\$1layer or multi\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))) and (((inter\$1layer near4 di\$1electric) or ild or idl) and barrier) or ((damascence or cu or copper) and barrier))) and (((dielectric adj3 constant) or k) adj5 (1\$2 or 2\$2 or 3\$2 or 4\$2))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 12:23
-	68907	pe\$1cvd or plasma adj6 (cvd or deposit\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 12:24

-	976	(((((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((inter\$1layer near4 di\$1electric) or ild or idl)) and (damascence or cu or copper)) or (((((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))) or (((((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((((inter\$1layer near4 di\$1electric) or ild or idl) and barrier) or ((damascence or cu or copper) and barrier)))) and (((dielectric adj3 constant) or k) adj5 (1\$2 or 2\$2 or 3\$2 or 4\$2))) or (((((((bi\$1layer or dual\$1layer or multi\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))) and (((inter\$1layer near4 di\$1electric) or ild or idl) and barrier) or ((damascence or cu or copper) and barrier))) and (((dielectric adj3 constant) or k) adj5 (1\$2 or 2\$2 or 3\$2 or 4\$2)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 12:25
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-	477	(((((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((inter\$1layer near4 di\$1electric) or ild or idl)) and (damascence or cu or copper)) or (((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))) or (((((bi\$1layer or dual\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and (((inter\$1layer near4 di\$1electric) or ild or idl) and barrier) or ((damascence or cu or copper) and barrier)))) and (((dielectric adj3 constant) or k) adj5 (1\$2 or 2\$2 or 3\$2 or 4\$2))) or ((((((bi\$1layer or dual\$1layer or multi\$1layer or composit\$3 adj3 layer) with (di\$1electric or insulator or insulating or insulation)) or (grad\$4 near5 (di\$1electric or k or constant))) and (low near3 ((dielectric adj3 constant) or k))) and ((damascence or cu or copper) or ((inter\$1layer near4 di\$1electric) or ild or idl))) and (((inter\$1layer near4 di\$1electric) or ild or idl) and barrier) or ((damascence or cu or copper) and barrier)))) and (((dielectric adj3 constant) or k) adj5 (1\$2 or 2\$2 or 3\$2 or 4\$2)))) and (pe\$1cvd or plasma adj6 (cvd or deposit\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 12:25
-	1645813	adhe\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 15:18
-	28718	adhe\$6 with barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 15:19
-	1687	(adhe\$6 with barrier) and (low near3 ((dielectric adj3 constant) or k))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 15:20
-	1480	((adhe\$6 with barrier) and (low near3 ((dielectric adj3 constant) or k))) and (damascence or cu or copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 15:20
-	797	((adhe\$6 with barrier) and (low near3 ((dielectric adj3 constant) or k))) and (damascence or cu or copper) and (pe\$1cvd or plasma adj6 (cvd or deposit\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 15:20